RELIABILITY REPORT

FOR

MAX6731AUTVD3+T

PLASTIC ENCAPSULATED DEVICES

May 13, 2015

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Conclusion

The MAX6731AUTVD3+T successfully met the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing products will continue to meet Maxim Integrated's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX6730A-MAX6735A single-/dual-/triple-voltage microprocessor (µP) supervisors feature a watchdog timer and manual reset capability. The MAX6730A-MAX6735A offer factory-set reset thresholds for monitoring voltages from +0.9V to +5V and an adjustable reset input for monitoring voltages down to +0.63V. The combination of these features significantly improves system reliability and accuracy when compared to separate ICs or discrete components. The active-low reset output asserts and remains asserted for the reset timeout period after all the monitored voltages exceed their respective thresholds. Multiple factory-set reset threshold combinations reduce the number of external components required. The MAX6730A/MAX6731A monitor a single fixed voltage, the MAX6732A/MAX6733A monitor two fixed voltages, and the MAX6734A/MAX6735A monitor two fixed voltages and one adjustable voltage. All devices are offered with six minimum reset timeout periods ranging from 1.1ms to 1120ms. The MAX6730A-MAX6735A features a watchdog timer with an independent watchdog output. The watchdog timer prevents system lockup during code execution errors. A watchdog startup delay of 54s after reset asserts allows system initialization during power-up. The watchdog operates in normal mode with a 1.68s delay after initialization. The MAX6730A/MAX6732A/MAX6734A provides an active-low, open-drain watchdog output. The MAX6731A/MAX6733A/MAX6735A provides an active-low, push-pull watchdog output. Other features include a manual reset input (MAX6730A/MAX6731A/MAX6734A/MAX6735A) and push-pull reset output (MAX6731A/MAX6733A/MAX6735A) or open-drain reset output (MAX6730A/MAX6732A/MAX6734A). The MAX6730A-MAX6733A is offered in a tiny 6-pin SOT23 package. The MAX6734A/MAX6735A are offered in an 8-pin, space-saving SOT23 package. All devices are fully specified over the extended -40°C to +125°C temperature range.

II. Manufacturing Information

A. Description/Function:	Single-/Dual-/Triple-Voltage µP Supervisory Circuits with Independent Watchdog Output
B. Process:	B8
C. Number of Device Transistors:	1073
D. Fabrication Location:	USA
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	July 22, 2006

III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0393
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115°C/W
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	230°C/W
M. Multi Layer Theta Jc:	76°C/W

IV. Die Information

A. Dimensions:	32 X 57 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% for all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 177 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 6.21 \times 10^{-9}$

$\lambda = 6.21$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25°C and 0.99 @ 55°C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The MS69-3 die type has been found to have all pins able to withstand an HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.

Table 1

Reliability Evaluation Test Results

MAX6731AUTVD3+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	177	0	

Note 1: Life Test Data may represent plastic DIP qualification lots.